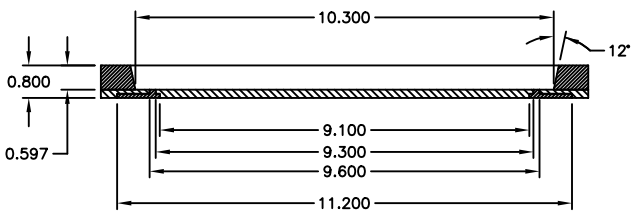
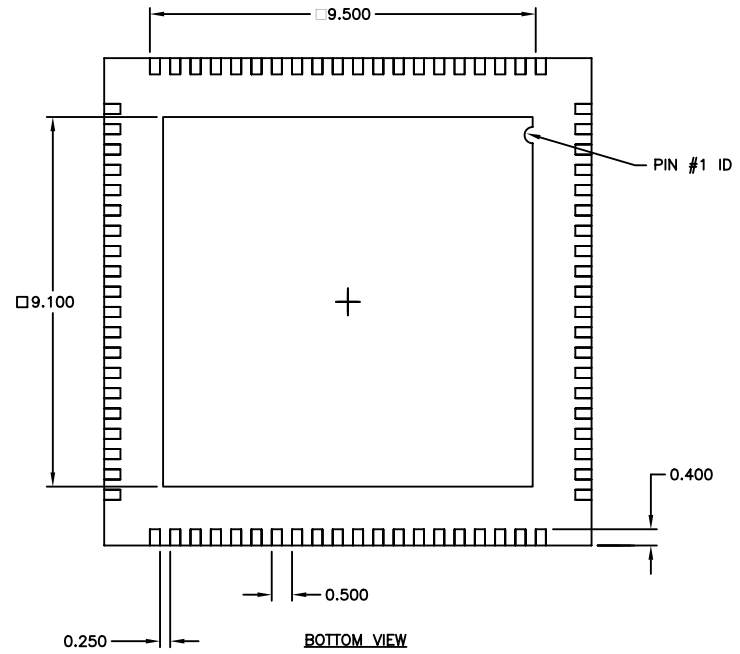
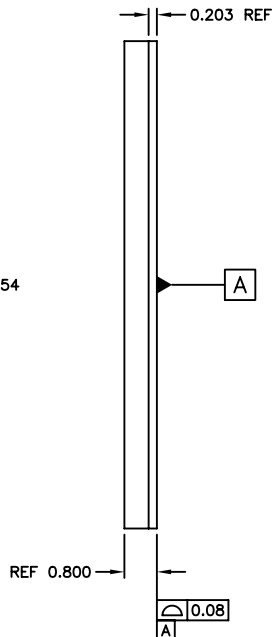
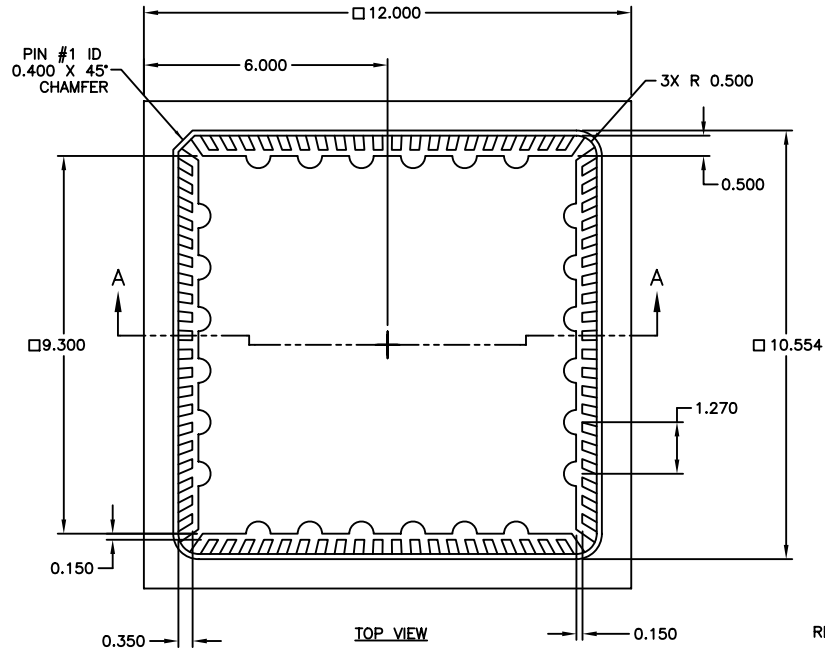


REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
	6/3/11	PRE-PRODUCTION RELEASE	S. SWEN



- NOTES**
- MATERIALS:**
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.
 - FINISH:**
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-28074, CLASS 1, 100 TO 300 MICROINCHES (2.5um - 7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um - 2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra).
 - PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX**
 - UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**
 - PACKAGE CONFORMS TO JEDEC MO-220.**

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN **MILLIMETER** TOLERANCES ARE:
 X.XX ± 0.15 X.XXXX ± ---
 X.XXX ± 0.050 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	CAD DEPT.	DATE	6/3/11
APP BY	STEVE S.	DATE	6/3/11
CUSTOMER	---		
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12mm X 12mm
 QFN 80 LEAD 0mPP

SIZE	PART NO.	REV
A	QP-QFN80-12-.5MM	A
SCALE	CAD FILE	SHEET
NONE		1 OF 1